AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method for providing a PCB (printed circuit board) with a shield can ~~(1;11;21;31)~~ comprising a metal shell having ~~with~~ a free rim ~~(5;15;25;35)~~, said method comprising the steps of:

providing the PCB ~~(12)~~ with solder; ~~(16),~~

placing the shield can ~~(1;11;21;31)~~ on the PCB ~~(12)~~ with the rim ~~(5;15;25;35)~~ towards the PCB; ~~(12),~~

heating the PCB ~~(12)~~ and the shield can ~~(1;11;21;31)~~ to a temperature above a melting temperature of the solder; and ~~(16),~~

cooling the PCB ~~(12)~~ and the shield can ~~(1;11;21;31)~~, wherein ~~characterised in that~~ the rim ~~(5;15;25;35)~~ of the shield can ~~(1;11;21;31)~~ is provided with an extra amount of solder ~~(8;18)~~ before the shield can ~~(1;11;21;31)~~ is placed on the PCB ~~(12)~~.

2. (Currently Amended) The ~~A~~ method according to claim 1, wherein ~~characterised in that~~ the rim ~~(5;15;25;35)~~ of the shield can ~~(1)~~ is provided with the extra amount of solder ~~(8)~~ by dipping the rim ~~it~~ partly into a bath of molten solder ~~(8)~~.

3. (Currently Amended) The ~~A~~ method according to claim 1, wherein ~~characterised in that~~ recesses ~~(19;29)~~ are provided at the rim ~~(15;25)~~ of the shield can ~~(11;21)~~ before the extra amount of solder ~~(18)~~ is applied thereto; and

wherein ~~that~~ the extra amount of solder ~~(18)~~ is applied to the recesses.

4. (Currently Amended) The ~~A~~ method according to claim 1 ~~or 3~~, wherein ~~characterised in that~~ the rim ~~(5;15;25)~~ of the shield can ~~(1;11;21)~~ is provided with the extra amount of solder ~~(8;18)~~ by a screen-printing process.

5. (Currently Amended) The ~~A~~ method according to claim 1 ~~or 2~~, wherein ~~characterised~~

~~in that~~ indentations ~~(39)~~ are provided at the rim of the shield can ~~(31)~~ before the extra amount of solder is applied thereto; and

wherein ~~that~~ the extra amount of solder is applied to the indentations ~~(39)~~.

6. (Withdrawn) A shield can (1;11;21;31) for electro-magnetically shielding an electronic component mounted on a printed circuit board (PCB) provided with solder, said shield can (1;11;21;31) comprising a metal shell with a free rim (5;15;25;35), characterised in that the rim (5;15;25;35) of the shield can (1;11;21;31) is provided with an extra amount of solder (8;18).

7. (Withdrawn) A shield can according to claim 6, characterised in that the rim (15;25) of the shield can (11;21) is provided with a plurality of recesses (19;29), each recess (19;29) being provided with an extra amount of solder (18).

8. (Withdrawn) A shield can according to claim 7, characterised in that each recess (19;29) is V-shaped.

9. (Withdrawn) A shield can according to claim 6, characterised in that the rim (35) of the shield can (31) is provided with a plurality of indentations (39), each indentation (39) being provided with an extra amount of solder.

10. (Withdrawn) A shield can according to claim 9, characterised in that each indentation (39) is V-shaped.

11. (Withdrawn) A shield can according to any one of claims 6-10, characterised in that the shield can (1;11;21;31) is box-shaped with a flat upper shell part (3;13) and four downwardly extending side pieces (4;14;24;34) with the free rim (5;15;25;35).

12. (Withdrawn) A shield can according to claim 11, characterised in that the side pieces (14;24;34) are interconnected at adjoining corners; and that each corner is provided with a leg (20) that protrudes downwards beyond the free rim (15;25;35).